L Number	Hits	Search Text	DB	Time stamp
-	1962	134/1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 11:32
-	59579	(shower adj head) or diffuser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 11:33
-	5651	(wafer or semiconductor) and ((shower adj head) or diffuser)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 11:42
-	174	WF6 and SiH4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 11:43
-	6	((wafer or semiconductor) and ((shower adj head) or diffuser)) and (WF6 and SiH4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 11:46
-	1803	'WF.sub.6' and 'SiH.sub.4'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 11:50
-	137	((shower adj head) or diffuser) and ('WF.sub.6' and 'SiH.sub.4')	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 11:52
-	103	(((shower adj head) or diffuser) and ('WF.sub.6' and 'SiH.sub.4')) and clean$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 11:53
-	1	((((shower adj head) or diffuser) and ('WF.sub.6' and 'SiH.sub.4')) and clean$3) and (showerhead or diffuser) same (cool$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 12:23
-	2316	remote adj plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 12:23
-	111	(remote adj plasma) and ('WF.sub.6' and 'SiH.sub.4')	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 12:28
-	8	((remote adj plasma) and ('WF.sub.6' and 'SiH.sub.4')) and 134/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 13:01
-	38	134/1.ccls. and ((shower adj head) or diffuser)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 14:01
-	52	((remote adj plasma) and ('WF.sub.6' and 'SiH.sub.4')) and ((showerhead or dispenser or diffuser) same (temperature or heat$3 or cool$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 14:34

—	51	(((remote adj plasma) and ('WF.sub.6' and 'SiH.sub.4')) and ((showerhead or dispenser or diffuser) same (temperature or heat$3 or cool$3))) and clean$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 14:50
—	266	134/1.ccls. and (clean$3 and (chamber or apparatus)).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 14:51
—	998	134/1.ccls. and method.ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 14:52
—	165	(134/1.ccls. and (clean$3 and (chamber or apparatus)).ti.) and method.ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 14:52
—	76	((134/1.ccls. and (clean$3 and (chamber or apparatus)).ti.) and method.ti.) and (wafer or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 15:12
—	488	134/1.1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 15:12
—	78	134/1.1.ccls. and (remote adj plasma)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 15:13
—	33	134/1.1.ccls. and ((shower adj head) or diffuser)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 15:17
—	1	134/1.ccls. and (heat$3 near showerhead)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 15:21
—	3	134/1.1.ccls. and heat$3 near showerhead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 15:21
—	3	134/1.1.ccls. and (heat$3 near showerhead)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 15:31
—	17	134/1.1.ccls. and (heat$3 near (showerhead or diffuser or distribut$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 15:32
—	1541008	wafer or semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 08:09
—	0	(wafer or semiconductor) and (((shower adj head) or diffuser) near (cool$3 near solution))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 08:11

–	13	((wafer or semiconductor) and (((shower adj head) or diffuser) near cool$3)) and clean$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 08:12
–	33	(wafer or semiconductor) and (((shower adj head) or diffuser) near cool$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 08:14
–	345	134/1.2.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 08:58
–	23	134/1.2.ccls. and showerhead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 09:27
–	197	216/69.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 09:30
–	10	216/69.ccls. and (showerhead or diffuser or (diffusion near plate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 10:22
–	0	118/723.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 10:22
–	1341	118/723e.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 10:23
–	68415	showerhead or (shower adj head) or diffuser or (diffusion adj plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 10:24
–	239	118/723e.ccls. and (showerhead or (shower adj head) or diffuser or (diffusion adj plate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 10:24
–	21	(118/723e.ccls. and (showerhead or (shower adj head) or diffuser or (diffusion adj plate))) and ((shower adj head) or diffuser or (diffusion adj plate)) same cool$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 11:01
–	8422	(showerhead or (shower adj head) or diffuser or (diffusion adj plate)) and (wafer or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 11:02
–	91	((showerhead or (shower adj head) or diffuser or (diffusion adj plate)) and (wafer or semiconductor)) and ((shower adj head) or diffuser or (diffusion adj plate)) near (temperature or '.deg.C')	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 11:04
–	91	((showerhead or (shower adj head) or diffuser or (diffusion adj plate)) and (wafer or semiconductor)) and ((shower adj head) or diffuser or (diffusion adj plate)) near (temperature or '.degree.C')	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 11:13

-	8	US-5935340-$.DID. OR US-6251776-$.DID. OR US-6417080-$.DID. OR US-6492276-$.DID.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 11:20
-	257	438/905.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 11:20
-	200	438/905.ccls. and plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 11:20
-	21	((438/905.ccls. and plasma) and microwave) and (showerhead or diffuser or (diffusion near plate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 11:55
-	65	"5788799"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 11:55
-	2	5788799.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 11:58
-	164	156/345.46.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 11:59
-	65877	156/345.46.ccls. and showerhead or (shower adj head) or diffuser or (diffusion adj plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 11:59
-	39	156/345.46.ccls. and (showerhead or (shower adj head) or diffuser or (diffusion adj plate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 13:37
-	4	US-4960488-$.DID. OR US-5939831-$.DID.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 13:38
-	57	(438/905.ccls. and plasma) and microwave	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 14:44
-	1	"5252178".PN.	USPAT; US-PGPUB	2004/09/24 14:33
-	1	"5356478".PN.	USPAT; US-PGPUB	2004/09/24 14:34
-	1	"6569257".PN.	USPAT; US-PGPUB	2004/09/24 14:36
-	730	134/19.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 14:44
-	165	134/19.ccls. and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 14:46

–	21	(134/19.ccls. and (semiconductor or wafer)) and microwave	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 14:48
–	257	438/905.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 16:12
–	0	438/905.ccls. and (microwave not plasma)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 14:49
–	57	438/905.ccls. and microwave	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 14:49
–	0	156/345.36.ccls. and (microwave not plasma)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 14:50
–	74	156/345.36.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 14:52
–	2	6635117.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 14:52
–	77	438/905.ccls. and tungsten	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 16:12
–	46	(438/905.ccls. and tungsten) and fluorine	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 16:15
–	20	((438/905.ccls. and tungsten) and fluorine) and microwave	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 16:15